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Support the European Industry in reinforcing its competitive advantage by accelerating the **integration of Flexible Electronics into novel products**

Innovation Action: Call: ICT- 04-2017

Number of partners: 10 partners (8 EU countries)

Grant: 4.5M€

Duration: 36 months

Expected results: 20 Application Experiments worth 2.8 M€ support (62% of the grant)



The SmartEEs project has received funding from the European Union's Horizon 2020 Research and Innovation program under Grant Agreement nº 761 496





2. Context - Smart Anything Everywhere

8 Digital Innovation Hubs sustaining the SAE initiative towards the digitization of the European Industry

Cluster Projects



EUROCPS

A network of design centres boosting and initiating synergies between SMEs, major CPS-platforms and competency providers to capture the emerging markets of IoT products. **30 experiments** initiated and led by SMEs.



CPSELABS

CPS engineering infrastructure, knowledge and tools for realising novel CPS-based products and services. The CPSELabs marketplace provides an open forum for sharing platforms, architectures and SW tools for the engineering of dependable and trustworthy CPS. Focussed experiments (3-6 partners) and fast-track (12-18 months) with innovation objective.



Innovation service for European smartization by SMEs. 20% of bioelectronics technologies. 50 small scale experiments to deliver innovation concept as demonstrators with SMEs engaged in testing phase.



Smart access to manufacturing for systems integration. To develop a RTO Community Foundry Model (CFM) that will accelerate a wider deployment of SSI with greater access to design, manufacturing capabilities for prototyping, early validation and first production for SMEs to exploit in niche markets (low volume high value). A test bed to realise 10 application experiments

ICT-04-2017

ICT-04-2014



tetramax





CYBER-PHYSICAL AND EMBEDDED SYSTEMS CUSTOMISED LOW ENERGY COMPUTING POWERING CPS AND IOT ADVANCED MICRO-ELECTRONIC COMPONENTS AND SMART SYSTEM INTEGRATION

LARGE AREA ELECTRONICS



SmartEEs - Acceleration program bringing flexible electronics product to life



What are Digital Innovation Hubs (DIHs)?

DIHs are **ecosystems** that consist of SMEs, large industries, start-ups, research technology organizations, innovation & business developers, investors, industrial clusters & associations, representatives of regional/national funding agencies,...

DIHs help ensuring that every company, small or large, high-tech or not, can grasp the digital opportunities.

DIHs aim at creating the best conditions for **long-term business** success for all parties involved.



3. Application - Flexible Electronics





SmartEEs - Acceleration program bringing flexible electronics product to life

An estimated 62 billion euros market by 2027 (source OE-A)

Automotive		Logistics	+ * +
Building & architecture	İ	Medical & pharmaceutical	\bigotimes
Consumer electronics		Packaging	
Energy		Printing & graphic arts	%
Lighting	— ! !	Textile & fashion	1
		Others	?

In comparison

- 2017 global semiconductor market: 320 billion euros (source Statistica)
- 2017 Smart sensor market: 49 billion euros (source Markets and markets)



An original European acceleration program dedicated to **outreach and help innovative companies to access new markets and grow their business in adopting flexible electronics** in new products lines

20 funded projects (Application Experiments) to be supported Up to 165k€ investment per project Call for projects – 5 cut off dates



4. Acceleration program A full set of actions to accelerate Flexible Electronics integration

For start-ups, SMEs and Mid-caps to:

Access Competencies

- Competencies in design and technologies integration
- Competencies in innovation management (business & funding)

Leverage up to 165 k€ investment

- Direct service (up to 80k€)
- Voucher financing (up to 60k€^{*})
- Up to 25k€^{*} of in-kind contribution
- Prepare next steps financing

70-30 % H2020 funding rules for Private Companies

Develop new product

- Bring new functionalities to your products
- Design a first prototype, scale-up study and sustainability
- Production agility: adapted for low to high volume markets



- New value chain building
- Strengthen competitive positioning
- Explore new markets



5. Value proposal Benefit from large portfolio of solutions to develop your product

Access to more than 35 electronics flexible solutions to design your product:

Organic photovoltaics Flexible displays OLED Lighting Electronics & components and Integrated Smart Systems





A high **complementarity of technologies** integrating flexible electronics into printings, textiles, paper, plastronics, HMIs,...

All inclusive features for **smart products & market entrance**: from hardware to software and connectivity with bespoke business models and value chains.

Access to an **unique community** with **business connections** and **brokerage activities at European level**.



5. Value proposal - Access to a unique community

A unique and connected international electronics landscape



🗾 Fraunhofer

EEB









10 partners

SmartEEs community

- $\sqrt{2}$ Associations
- √ 34 Clusters
- $\sqrt{8}$ Investors
- ✓ 18 Industrial companies
- \checkmark New entrants

eurecal









SmartEEs - Acceleration program bringing flexible electronics product to life

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✓ New products and new business models

- ✓ Market *revenues increase* for innovative companies & whole ecosystem
- ✓ Contribution of *private investments*
- ✓ *Enlarged community* & ecosystem
- ✓ *Sustainability* of SmartEEs with continuity plan



- SMEs, start-ups and Midcaps
- **Tech** (innovative companies) **or non tech** (traditional industries)
- From all activities fields

Automotive		Logistics	+
Building & architecture	İ h	Medical & pharmaceutical	\bigotimes
Consumer electronics	٩ ٩	Packaging	
Energy		Printing & graphic arts	%
Lighting	A	Textile & fashion	1
		Others	?





6. Application Experiments - How to apply

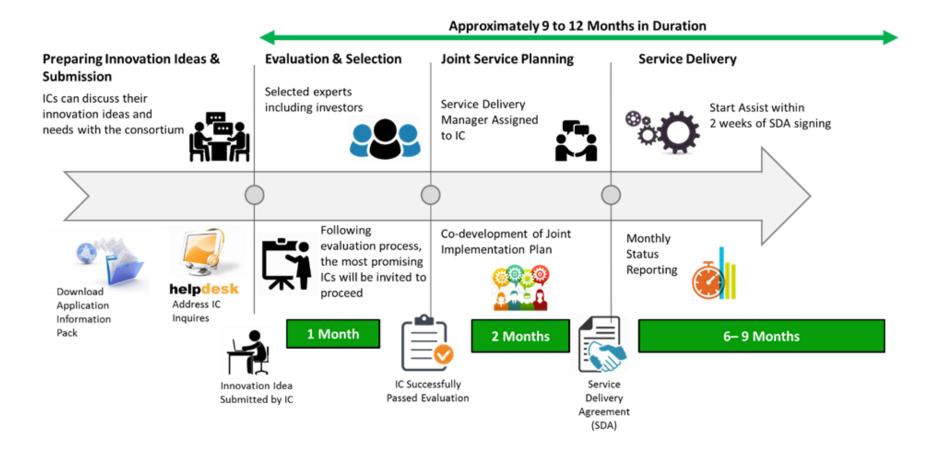
- 1. Check out the SmartEEs Showroom on the web platform www.smartees.eu
- 2. Discover & review more than 35 electronics flexible solutions to feed your product ideas
- 3. Download the Call documents
 - Text of the Call
 - Application Form
 - Application Guidelines
 - SmartEEs Financial Guidelines for Application Experiments
 - Service Delivery Agreement (SDA)
- 4. Submit your project online through the application form
- 5. Contact the HelpDesk if any inquiries





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(IC = innovative company = third party beneficiary of SmartEEs)





Open call calendar

5 cut-off dates:

1st Cut-off	19th of March 2018
2nd Cut-off	20th of July 2018
3rd Cut-off	16th of November 2018
4th Cut-off	19th of April 2019
5th Cut-off	20th of September 2019







- www.smartees.eu
 - Linkedin : SmartEEsEU
 - Twitter : @SmartEEsEU

SmartEEs project coordinator

Jérôme GAVILLET: jerome.gavillet@cea.fr

SmartEEs project manager

Minja MARIC: maric@amires.eu





